Super Fast Recovery Diode
RF1501TF3S

- **Series**
  - Standard Fast Recovery

- **Applications**
  - General rectification

- **Features**
  1) Ultra low switching loss
  2) High current overload capacity

- **Construction**
  - Silicon epitaxial planer

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### Dimensions (Unit: mm)

- **Structure**

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### Absolute maximum ratings (Tc=25°C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Limits</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Repetitive peak reverse voltage</td>
<td>VRM</td>
<td>Duty≤0.5</td>
<td>350</td>
<td>V</td>
</tr>
<tr>
<td>Reverse voltage</td>
<td>VR</td>
<td>Direct voltage</td>
<td>300</td>
<td>V</td>
</tr>
<tr>
<td>Average rectified forward current</td>
<td>Io</td>
<td>60Hz half sin wave, Resistance load, Tc=37°C</td>
<td>20</td>
<td>A</td>
</tr>
<tr>
<td>Forward current surge peak</td>
<td>IFSM</td>
<td>60Hz half sin wave, Non-repetitive one cycle peak value, Tj=25°C</td>
<td>100</td>
<td>A</td>
</tr>
<tr>
<td>Junction temperature</td>
<td>Tj</td>
<td></td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Storage temperature</td>
<td>Tstg</td>
<td></td>
<td>-55 to +150</td>
<td>°C</td>
</tr>
</tbody>
</table>

### Electrical characteristics (Tj=25°C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Forward voltage</td>
<td>VF</td>
<td>I_F=20A</td>
<td>—</td>
<td>1.35</td>
<td>1.5</td>
<td>V</td>
</tr>
<tr>
<td>Reverse current</td>
<td>IR</td>
<td>V_R=300V</td>
<td>—</td>
<td>0.06</td>
<td>10</td>
<td>μA</td>
</tr>
<tr>
<td>Reverse recovery time</td>
<td>tr</td>
<td>I_F=0.5A, I_R=1A, I_T=0.25×I_R</td>
<td>—</td>
<td>22</td>
<td>30</td>
<td>ns</td>
</tr>
<tr>
<td>Thermal resistance</td>
<td>Rth(j-c)</td>
<td>junction to case</td>
<td>—</td>
<td>—</td>
<td>3</td>
<td>°C/W</td>
</tr>
</tbody>
</table>
RF1501TF3S

Data Sheet

**I_{FSM} DISPERSION MAP**

- **Forward Current** \( I_{FSM} \) vs. Time (ms)
- AVE: 216.5A
- 1cyc
- 8.3ms

**trr DISPERSION MAP**

- **Reverse Recovery Time** \( trr \) (ns)
- AVE: 19.3ns
- \( t = 0.5A \)
- \( I_R = 1A \)
- \( Tj = 25^\circ C \)

**PEAK SURGE FORWARD CURRENT** \( I_{FSM} \) (A)

- \( C = 200\mu F \) R=0
- \( C = 100\mu F \) R=1.5k

- **No break at 30kV**

**ELECTROSTATIC DISCHARGE TEST** ESD (KV)

- **ESD DISPERSION MAP**
- \( C = 200\mu F \) R=0
- \( C = 100\mu F \) R=1.5k

**TRANSIENT THERMAL IMPEDANCE** \( R_{th(t)} \) (°C/W)

- **THERMAL IMPEDANCE** \( R_{th} \) CHARACTERISTICS
- Rth(t) vs. Time (s)

**NUMBER OF CYCLES** \( I_{FSM} \)-CYCLE CHARACTERISTICS

- \( t_{FSM} \)
- 1cyc
- 8.3ms

**TIME** \( t \) (ms)

- \( I_{FSM} \)-t CHARACTERISTICS
- \( t_{FSM} \)
- 8.3ms

- \( I_{FSM} \)
- 1cyc
- 8.3ms

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Forward Power Dissipation: \( P_f (W) \)

Average Rectified Forward Current: \( I_o (A) \)

Derating Curve: \((I_o - T_a)\)

Case Temperature: \( T_c (°C) \)

Ambient Temperature: \( T_a (°C) \)

Equation:

\[ T_j = 150°C \]

\[ D = \frac{t}{T} \]

\[ V_R = 280V \]

\[ V_c = 290V \]

\[ T_j = 150°C \]

\[ T_c = T_j - D \]

Symbols:

- \( P_f \): Forward Power Dissipation
- \( I_o \): Average Rectified Forward Current
- \( T_j \): Junction Temperature
- \( T_c \): Case Temperature
- \( V_R \): Forward Voltage
- \( V_c \): Case Voltage
- \( T \): Period
- \( t \): Time

Graphs show the relationship between these variables for different duty cycles and ambient temperatures.
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(Note1) Medical Equipment Classification of the Specific Applications

<table>
<thead>
<tr>
<th>JAPAN</th>
<th>USA</th>
<th>EU</th>
<th>CHINA</th>
</tr>
</thead>
<tbody>
<tr>
<td>CLASSⅢ</td>
<td>CLASSⅢ</td>
<td>CLASSⅡb</td>
<td>CLASSⅢ</td>
</tr>
</tbody>
</table>

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[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

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[a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
[b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
[c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
[d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
[e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
[f] Sealing or coating our Products with resin or other coating materials
[g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
[h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification
Precautions Regarding Application Examples and External Circuits
1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic
This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation
1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label
QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition
When disposing Products please dispose them properly using an authorized industry waste company.

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Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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